



Bridge to the Sustainable Growth
with Innovative Integrated Electronic Systems
*From super low power edge computing
and car electronics to AI systems*

3rd CIES Technology Forum

March 21 - 22, 2017

DAY 1

Registration

[www.cies.tohoku.ac.jp/
3rd_forum/entry.html](http://www.cies.tohoku.ac.jp/3rd_forum/entry.html)

Registration fee: Free

Banquet fee: 7,000JPY

Pre-registration deadline:

March 14, 2017

**Tohoku University
Center for Innovative Integrated
Electronic Systems**

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International Symposium

March 21, 2017

Station Conference Tokyo, Sapia Tower 5F, 501ABS
1-7-12 Marunouchi, Chiyoda-ku, Tokyo

Invited Speakers

David Eggleston (GLOBALFOUNDRIES)
Hideto Hidaka (Renesas Electronics)
Hiroaki Honjo (Tohoku University)
Seung H. Kang (Qualcomm)
Masaaki Kuzuhara (Fukui University)
Tetsuzo Ueda (Panasonic)
Yoonjong Song (Samsung)

Chair

T. Endoh (Tohoku Univ.)

Committee

S. Ikeda, K. Ito, M. Niwa,
H. Koike (Tohoku Univ.)

Secretariat

T. Shinada, Y. Kadowaki (Tohoku Univ.)

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<<<Registration desk open at 9:45am>>>

10:30-10:45	Opening remarks	Tetsuo Endoh (Tohoku University)
10:45-11:25	<i>Invited talk 1</i> What's Next for MRAM beyond Early Adopters?	Seung H. Kang (Qualcomm)
11:25-12:05	<i>Invited talk 2</i> Overview and challenge of current embedded STT-MRAM technology	Yoonjong Song (Samsung)
12:05-12:45	<i>Invited talk 3</i> Material development in advanced STT-MRAM for non-volatile VLSI	Hiroaki Honjo (Tohoku University)
12:45-14:20	Lunch	
14:20-15:00	<i>Invited talk 4</i> How Future Embedded Mobility Meets IT - Embedded cyber-physical system designs revisit semiconductor technology -	Hideto Hidaka (Renesas Electronics)
15:00-15:40	<i>Invited talk 5</i> eMRAM: The march to manufacturing	David Eggleston (GLOBALFOUNDRIES)
15:40-16:00	Break	
16:00-16:40	<i>Invited talk 6</i> GaN-based HEMT Technology for Low-loss and High-voltage Operation	Masaaki Kuzuhara (Fukui University)
16:40-17:20	<i>Invited talk 7</i> Recent Progress in GaN Power Devices	Tetsuzo Ueda (Panasonic)
17:20-17:30	Closing remarks	Shoji Ikeda (Tohoku University)
18:00-19:30	Banquet (Station Conference Tokyo, Sapia Tower 4F, 402ABCD)	

Inquiry

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